

5 MINUTE EPOXY

Rapid Curing, High Strength, General Purpose Epoxy Adhesive

Description: **DEVCON® 5 Minute Fast Drying Epoxy** is a rapid curing, high strength, general purpose epoxy adhesive / encapsulant. It forms a clear, hard, rigid bond or coating in minutes.

Intended Use:

- 7 minute fixture time
- 100% reactive, no solvents
- Good dielectric strength
- Bonds metal, fabrics, ceramics, glass, wood and concrete (in combinations)
- Good solvent resistance

Product Features:

- **Cures fast for quick metal to metal bonding and repairs.**
- **Pots and encapsulates electronic components and assemblies.**
- **Seals against dust, dirt and combination.**
- **Fast curing, thin set, bonding above 5°C.**

Typical Physical Properties:

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Colour	Clear
Mix Ratio by volume	1:1
Mixed Viscosity	8000-10000 cps
Working time 28gm @ 24°C	4 minutes
Functional cure @ 24°C	45 minutes
Coverage based on 25ml	980cm ² @ 0.25mm
% Solids by volume	100

TEST METHODS

Performance Characteristics 7 days cured @ 24°C

Adhesive tensile shear	9.6 MPa	ASTM D1002
Operating temperature – dry	-40°C to + 93°C	
Cured density	1.10 gm/cm ³	ASTM D792
Cured hardness	85D	ASTM D2240
Dielectric strength	490 volts/mil	ASTM D149

Surface Preparation:

5 Minute epoxy works best on clean surfaces. Surfaces should be solvent wiped free of heavy deposits of greases, oil, dirt and other contaminants, or cleaned with industrial cleaning equipment such as vapour phase degreasers or hot aqueous baths. Abrading or roughening the surfaces of metals will increase the microscopic bond area significantly and optimise the bond strength.

Mixing Instructions:

1. Squeeze material into a small container
2. Using mixing stick included on Dev-tube handle, vigorously mix components for (1) minute
3. Immediately apply to substrate.

Application Instructions:

Apply mixed epoxy directly to one surface in an even film or as a bead. Assemble with the mating part within the recommended working time. Obtain firm contact between the parts to minimise any gap and ensure good contact of the epoxy with

the mating part. A small fillet or the epoxy should flow out the edges to show there is adequate gap filling. For very large gaps apply epoxy to both surfaces and spread to cover the entire area, or make a bead pattern which will allow flow throughout the joint.

Let bonded assemblies stand for the recommended cure time before handling. They are capable of withstanding processing forces at this point, but should not be dropped, shock loaded or heavily loaded.

Storage: Store in dry conditions away from sources of heat and naked flames. Protect from frost. When stored in original sealed containers, the minimum shelf life is three years.

Warranty: Devcon® will replace any material found to be defective. Because the storage, handling and application of this material is beyond our control, we can accept no liability for the results obtained.

Disclaimer: All information on this data sheet is based on laboratory testing and is not intended for design purposes. ITW Polymers & Fluids and Devcon® makes no representations or warranties of any kind concerning this data.

Order Information: 24.8gm DS-208

Health & Safety Information: For Health & Safety Information, refer to Safety Data sheet available from ITW Polymers & Fluids upon request on our website www.devcon.com.au or www.devcon.co.nz

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